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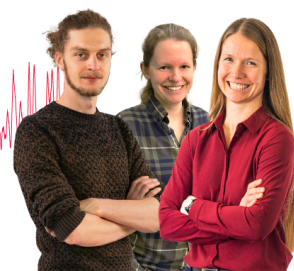
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Observation of trap-assisted space charge limited conductivity in short channel MoS₂ transistor

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We present temperature dependent I - V measurements of short channel MoS₂ field effect devices at high source-drain bias. We find that, although the I - V characteristics are ohmic at low bias, the conduction becomes space charge limited at high V_{DS} , and existence of an exponential distribution of trap states was observed. The temperature independent critical drain-source voltage (V_c) was also determined. The density of trap states was quantitatively calculated from V_c . The possible origin of exponential trap distribution in these devices is also discussed. © 2013 AIP Publishing LLC.
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The MoS₂-based transistors have drawn a considerable interest in recent years because of their wide variety of applications like high on/off ratio transistor,¹ phototransistor,² non-volatile memory device,³ tunnel barrier transistor,^{4,5} photodetector,⁶ etc. Although the device architectures with MoS₂ have been well-explored, there are only few studies on the fundamental aspects of these devices like low mobility, localized electronic states, and strongly disordered electronic landscape. The localized nature of electronic states has been reported by different groups and was explained either by variable range hopping (VRH)^{7,8} or temperature dependent activated behavior^{9,10} but the origin of such strong disorder remained unaddressed. It was suggested that the substrate trap charges might be responsible for the localization⁷ because ultrathin flakes are often found to be influenced more by substrate induced external potentials. On the other hand, many similar low mobility systems such as organic semiconductors^{11,12} and reduced graphene oxide transistors¹³ have been investigated, where traps were found to originate from bulk due to structural inhomogeneity inside the materials. The present work was motivated to find whether the manifestation of strong localization in MoS₂ is substrate effect or there is some generic source of disorder in the bulk of MoS₂.

It is well-known that distribution of trap states can be addressed by measuring I - V characteristics at high source-drain bias when device characteristics are determined by space charge limited conductivity (SCLC). The SCLC occurs when the injected carrier density (n) at high V_{DS} exceeds the intrinsic carrier density (n_0) of the material at that temperature (T). For a trap free solid, the SCLC theory predicts that although the I - V characteristic is ohmic at low V_{DS} , it changes to $J_{MG} = \frac{9}{8} \mu \epsilon_0 \epsilon_r \frac{V_{DS}^2}{L^3}$, which is known as Mott-Gurney relation (J is current density, whereas μ , ϵ_r , and L are mobility, relative permittivity, and length of the solid between two electrodes). In the presence of exponential trap charge distribution $h(E) = \frac{N_t}{k_B T_c} e^{-E/k_B T_c}$ in the solid, the current-voltage relation becomes¹⁴

$$J_T = \frac{\mu N_c}{q^{m-2}} \left(\frac{2m-1}{m} \right)^m \left(\frac{\epsilon_0 \epsilon_r (m-1)}{N_t m} \right)^l \frac{V^m}{L^{2m-1}}, \quad (1)$$

where N_t and T_c are the total trap density and characteristic temperature of the trap distribution, N_c is the effective density of states in conduction band, $m = \frac{T}{T_c} + 1$. When the measurements are done at $T \leq T_c$, $m \geq 2$. Therefore, the exponent becomes 2 at T_c and monotonically increases as T decreases below T_c . This technique has already been widely used to explore the nature of trap states in past, particularly, for low mobility devices.^{13,15,16} In this study, we perform output characteristics (I - V) of short channel MoS₂ transistors at high source drain bias, i.e., longitudinal electric field. We find that at low V_{DS} , the I - V characteristics are ohmic, i.e., $I_{DS} \propto V_{DS}^m$, where $m=1$ but as the electric field increases m increases from one and reaches $m \approx 2$ at room temperature. The exponent m further increases monotonically as temperature decreases, indicating a trap dominated SCLC.

Single layer of MoS₂ sheets was exfoliated using bulk MoS₂ crystals (SPI supplies) on 285 nm degenerately doped Si/SiO₂ wafers by micromechanical cleavage technique using scotch tape. Before exfoliation, the Si/SiO₂ wafers were thoroughly cleaned by RCA1 (5:1:1 of H₂O:NH₄OH:H₂O₂) solution for 15 min and then in acetone and isopropyl alcohol in a ultrasonic bath. The layer number was identified using optical microscope color contrast¹⁷ and Raman spectroscopy.¹⁸ The devices were prepared by ebeam lithography, metallization of 50 nm Au, and liftoff in hot acetone. The channel lengths were kept smaller (typically from 80 to 200 nm) to achieve high longitudinal electric field at relatively lower V_{DS} . A schematic of the 2-probe device is shown in Figure 1(a), whereas the inset of Figure 1(b) shows the SEM image of Dev1 (see Table I). The transfer characteristic (I - V_{BG} , shown in Figure 1(b)) was measured using lockin technique. From the transfer characteristics, all the devices were found to be highly n -doped even at $V_{BG} = 0$ V and the pinch-off voltage⁷ (V_{ON}) was below $V_{BG} = -40$ V in most of the devices (see supplementary¹⁹ Figure S1 and Table 1). The field effect mobility (μ_{FE}) was calculated from the slope of I - V_{BG} graph (Figure 1(b)) for all the devices which came out to be about 0.3–2 cm²/Vs (see Table I).

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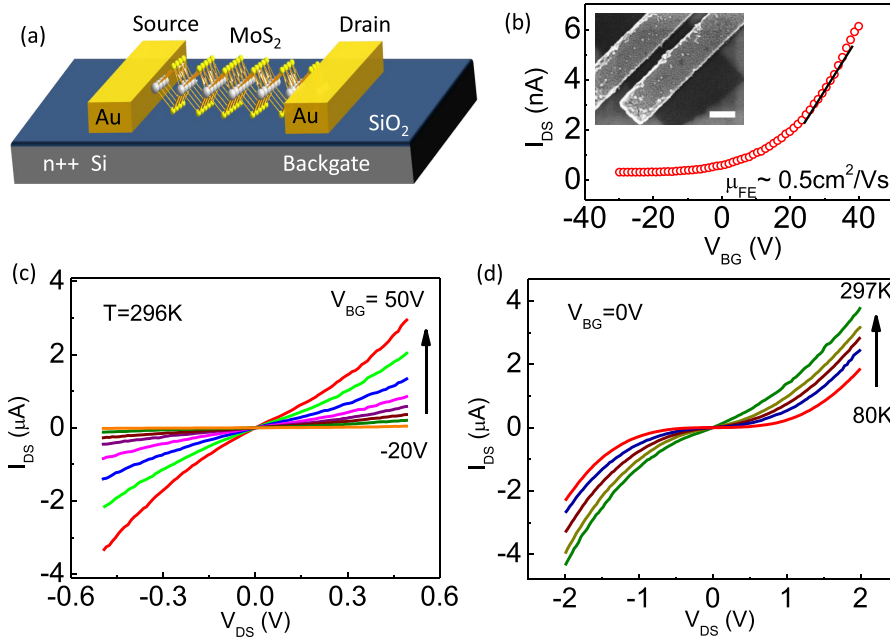


FIG. 1. (a) Schematic of a 2-probe single layer MoS₂ device on Si/SiO₂ wafer. (b) Transfer characteristic of Dev 2 at room temperature and V_{DS} = 10 mV. Field effect mobility was calculated from the slope of the curve as shown with the black line. Inset shows the SEM image of Dev 1 with scale bar 150 nm. (c) *I*-*V* characteristics of Dev 6 at room temperature and V_{BG} from 50 V to -20 V with 10 V gap. (d) *I*-*V* characteristics of Dev 4 at V_{BG} = 0 V at 80, 160, 200, 240, and 297 K.

The output characteristics (*I*-*V*) were measured at various temperatures using two DC voltage sources (Keithley 2400) acting as V_{DS} and V_{BG}. Figure 1(c) shows the *I*-*V* characteristics near room temperature at different V_{BG}. It is clear from the graph that the *I*-*V* characteristics are highly symmetric and linear for V_{DS} ≤ 100 mV (see supplementary material for details). This can be attributed to the quasi-ohmic nature of the contacts between MoS₂ and Au, already discussed in literature.²⁰ It has also been recently reported from a density functional theory (DFT) calculation that the interface of MoS₂-Au contact becomes metallic which can give rise to ohmic contact.²¹ Moreover, experimental determination of work function reveals that for single layer MoS₂, its work function reaches 5.1 eV from the bulk value 4.5 eV, which is similar to the work function of Au,²² indicating a high possibility of ohmic contact at the interface. In our experiment, we see that the *I*-*V* characteristics slowly become non-linear as V_{DS} increases but always remain symmetric indicating absence of dominant Schottky barrier at the junction. Although many experimental studies have recently reported current saturation at high V_{DS} in the presence of high gate electric field,^{23–25} we saw a strong increase in current after the ohmic regime till breakdown (see supplementary material). Figure 1(d) represents output characteristics

till V_{DS} = 2 V at V_{BG} = 0 V at different *T*. Two important things to note are as follows: (i) the *I*-*V* characteristics are symmetric with a non-linearity which increases as *T* decreases and (ii) strongly *T* dependent in the experimental temperature range. These observations effectively eliminate any significant effect of Schottky barrier or field induced tunneling (direct or Fowler-Nordheim tunneling) in the conduction process.

The room temperature *I*-*V* characteristics of three different devices are plotted in Figure 2(a) in log-log scale. We found that for V_{DS} ≤ 500 mV, I_{DS} ∝ V_{DS}^{*m*} with *m* = 1, indicating ohmic conduction in the sample. With further increase of V_{DS}, the curves deviated from linearity and became I_{DS} ∝ V_{DS}^{*m*} with *m* ≈ 2. This suggests an initiation of trap-free space charge limited conductivity regime. Although space charge limited conductivity may originate from drain induced barrier lowering (DIBL) in short channel devices, we exclude their dominance owing to the recent report,²⁰ showing extreme robustness of MoS₂ devices against short channel effects. The temperature dependent of *I*-*V* characteristics for Dev 5 is shown in Figure 2(b). We found the slope of the curve at *T* = 285 K to be 1.7, which is little less than theoretically predicted value *m* = 2. We also saw the exponent *m* to be little lower than 2 in few other devices near room temperature. Probably, this happens because room temperature is greater than *T*_c for these devices, i.e., the devices have higher free electron concentration than the trapped ones. We see that as temperature goes down to 205 K, the exponent *m* reaches 2 and monotonically decreases with further lowering of temperature and reaches 3 at 105 K (Figure 2(c)). These observations clearly reveal existence of exponentially distributed trap states in the ultra-thin MoS₂ devices.

One of the key aspects of trap limited space charge conductivity is that the density of the trap states (*N*_t) can be quantitatively determined from the experimentally measured *I*-*V* characteristics. It is believed that as V_{DS} increases the trap states slowly get filled up by injected charge carriers. At

TABLE I. Details of the devices.

Device	Dimension (L × W) ^a	V _{ON} ^b	μ _{FE} ^c	V _c (V)	N _t (10 ¹⁷ cm ⁻³)
Dev 1	0.08 × 1.6	≫ -40	0.7	3	1.6
Dev 2	0.09 × 1.7	≫ -40	1.4	3.2	1.7
Dev 3	0.17 × 1.9	~ -15	0.4
Dev 4	0.16 × 1.9	> -40	0.5	3	1.6
Dev 5	0.22 × 2.0	~ -40	0.8	4.3	2.3
Dev 6	0.16 × 1.3	~ -70	0.7	2.8	1.5

^aBoth dimensions in μm.

^bIn V (approx.).

^cIn cm²/Vs at 295 K (approx.).

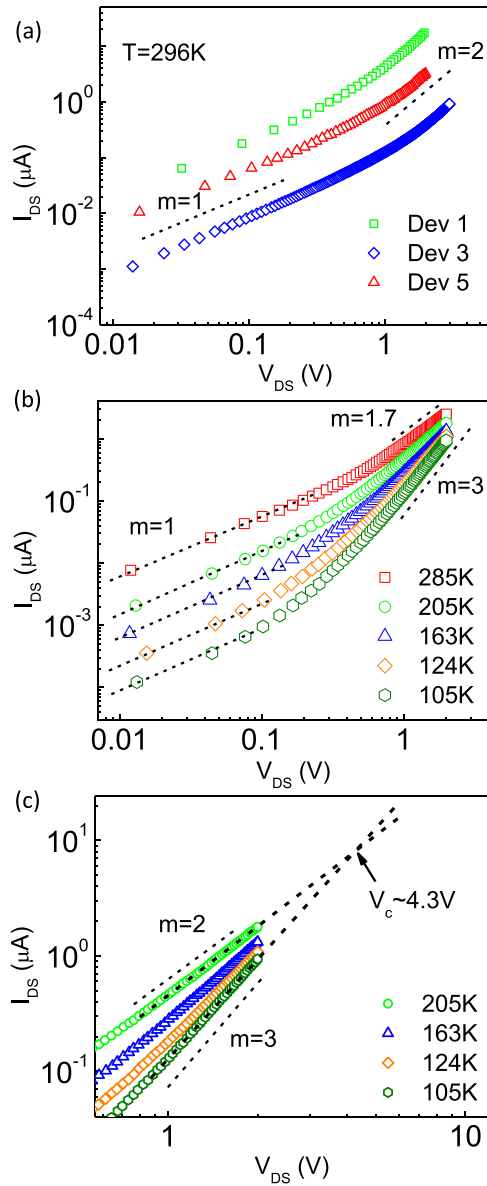


FIG. 2. (a) I - V characteristics of three different devices at room temperature and $V_{BG}=0$ V. (b) I - V characteristics of Dev 5 at different temperatures at $V_{BG}=10$ V. (c) Extrapolation of 105, 124, 163, and 205 K data derived from Figure 2(b) to extract V_c .

a critical V_{DS} , conductivity of the sample becomes independent of T , i.e., the I - V characteristics of different temperatures intersect each other. This critical voltage is called V_c and given by¹⁵

$$V_c = \frac{qN_t L^2}{2\epsilon_0 \epsilon_r}. \quad (2)$$

Therefore, V_c can be obtained by extrapolating the I - V curves at different T . This has been illustrated in Figure 2(c), where we extrapolate the I - V characteristics at $T=205$, 163, 124, and 105 K. The extrapolated lines intersect each other at a critical $V_{DS}=4.3$ V and trap density can be estimated to be $\sim 2.3 \times 10^{17} \text{ cm}^{-3}$ for Dev 5 (see the table for other devices). We believe that these traps originate from the bulk of the crystal and they are not interface trap states as discussed in a previous study.⁷ Therefore, the trap density is given in cm^{-3} .

We additionally study how the I - V characteristics change with increasing free carrier density in the channel using the backgate. It is obvious that as the free carrier density increases more and more trap states will be filled at $V_{DS}=0$ V. As a result, the effective density of trap states will reduce. Therefore, V_c will decrease with increasing V_{BG} owing to Eq. (2). This has been illustrated in Figure 3, where we plot the I - V characteristics of the same device at $V_{BG}=0$, 20, and 40 V. The critical source-drain voltage V_c was calculated for $V_{BG}=0$ and 20 V by extrapolating the I - V curves at 80, 110, 140, and 175 K yielding $V_c=2.8$ and 2.2 V, respectively (Figures 3(a) and 3(b)). With further increase of V_{BG} to 40 V, the I - V curves intersect each other at 1.4 V (Figure 3(c)). We did not include the 230 and 262 K data because we believe that at these elevated T (typically $T > 200$ K), the free carrier density slowly exceeds the trapped ones and calculation of V_c from Eq. (1) is not appropriate anymore. This can be easily understood from Figure 3(c), where I - V characteristics at $T=80$, 110, 140, and 175 K intersect each other, the graphs at 230 and 262 K show no signature of intersection till $V_{DS}=2$ V.

The origin of trap states in ultra-thin MoS_2 transistor remains controversial till date. Experimentally, it was found that the charge transport is governed by charged impurity scattering⁷ and presence of a high- k dielectric environment can improve the mobility by orders of magnitude,^{1,26} which leads to a prediction that the uncompensated dangling bonds at SiO_2 surface act as trap states and strongly affect the carrier conduction in MoS_2 .⁷ However, our present measurement confirms that apart from the substrate, there is an exponentially distributed trap state in MoS_2 , which might be more influential for carrier localization. To explore this quantitatively, we use the value of N_t and calculate the

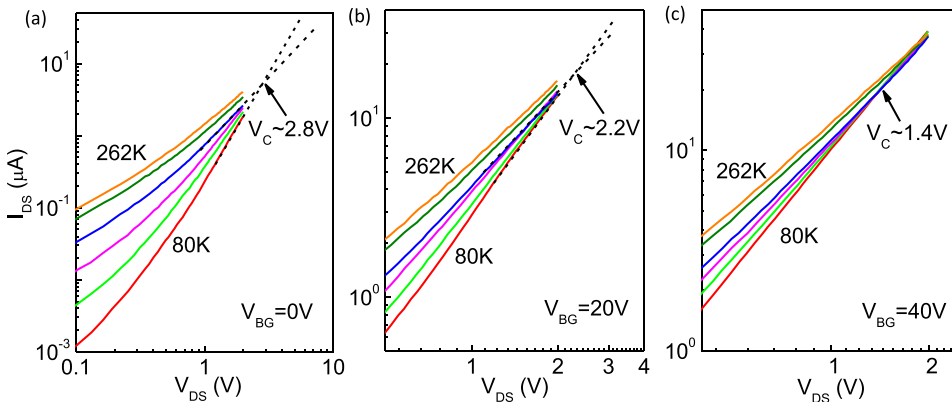


FIG. 3. Determination of V_c from the temperature dependent I - V characteristics for Dev 4 at (a) $V_{BG}=0$ V, (b) 20 V, and (c) 40 V. The characteristics were taken at 80, 110, 140, 175, 230, and 262 K.

correlation energy (T_0) of variable range hopping, known to be the transport mechanism in ultrathin MoS₂ devices.⁷ Assuming that the trap charges are distributed in an energy bandwidth of eV_c , we find $T_0 = \frac{1}{k_B \xi^3 (N_t/eV_c)}$ to be $2 \times 10^5 - 2 \times 10^4$ K using typical localization length $\xi \approx 10 - 20$ nm, which agrees well with experimentally observed T_0 values.⁷ It is believed that exponential trap distribution arises due to surface defect or structural disorder in the bulk of the sample.^{13,27} Similarly, inhomogeneity in MoS₂ may arise from external doping entity or point defects such as sulphur vacancies²⁸ (responsible for *n*-type doping) in crystal lattice. Moreover, it has also been predicted that the presence of atmospheric oxygen can lead to a minute oxidation of MoS₂ to form MoO₃ at the surface,²⁹ which can lead to structural disorder giving rise to trap states as found in case of reduced graphene oxide transistors.¹³

In conclusion, we study temperature dependent *I*-*V* characteristics in short channel MoS₂ transistors at high V_{DS} , i.e., longitudinal electric field. We find that the conduction is space charge limited at high V_{DS} with an exponentially distributed trap states. The trap density was qualitatively calculated measuring the temperature independent critical voltage V_c . We also discuss possible origin of such exponential trap distribution.

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